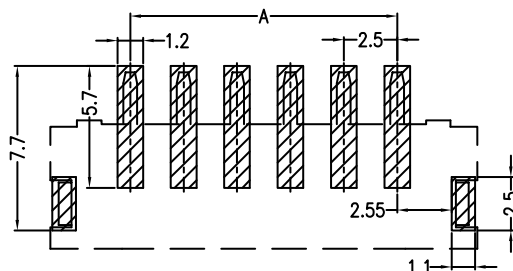
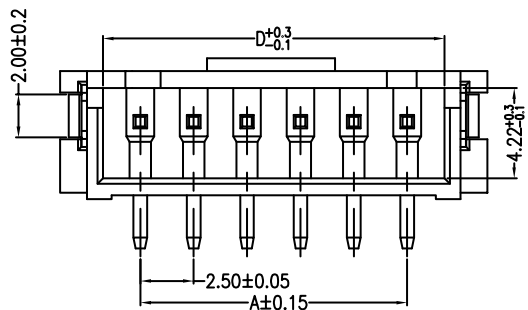


Assembly Layout

Main Specifications

- Contact resistance : $\leq 20m\Omega$
- Insulation resistance : $\geq 1000M\Omega$
- Rated voltage : 250V AC DC
- Rated current : 3.0A AC DC
- Withstand Voltage : 1000V AC/minute
- Temperature Range : $-25^{\circ}C \sim +85^{\circ}C$



SUGGESTED PCB LAYOUT

Circuit	Dimensions(mm)				Circuit	Dimensions(mm)			
	A	B	C	D		A	B	C	D
02	2.50	7.50	10.00	6.00	10	22.50	27.50	30.00	26.00
03	5.00	10.00	12.50	8.50	11	25.00	30.00	32.50	28.50
04	7.50	12.50	15.00	11.00	12	27.50	32.50	35.00	31.00
05	10.00	15.00	17.50	13.50	13	30.00	35.00	37.50	33.50
06	12.50	17.50	20.00	16.00	14	32.50	37.50	40.00	36.00
07	15.00	20.00	22.50	18.50	15	35.00	40.00	42.50	38.50
08	17.50	22.50	25.00	21.00	16	37.50	42.50	45.00	41.00
09	20.00	25.00	27.50	23.50					

一般公差 TOLERANCES X .±0.40 .XX ±0.20 .X ±0.30 .XXX ±0.10 ANGLES ±2°		深圳市宏利电子有限公司 Shenzhen Holy Electronic Co.,Ltd	
检验尺寸标示 SYMBOLS INDICATE CLASSIFICATION DIMENSION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.	工程图号 XHB25LB-nP	制图 (DR) *12/5/16 审核 (CHKD)	
表面处理 (FINISH)	比例 (SCALE) 1:1	单位 (UNITS) mm	核准 (APPD) Rigo Lu 张数 (SHEET) 1 OF 1 尺寸 (SIZE) A4 版本 (REV) 0

修订 REV	修改摘要 REVISION DESCRIPTION	日期 DATE	签名 SIGNATURE